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(JWES/JSA)

Solder paste — Part 1: Kinds and quality classification

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In the event of any doubts arising as to the contents,
the original JIS is to be the final authority.

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Contents

Page

Introduction ······ 1
1 Scope ······ 1
2 Normative references ······ 1
3 Terms and definitions ······ 2
4 Kinds ······ 2
5 Designation of products ······ 5
6 Quality ······ 5
7 Test methods ······ 6
7.1 Surface condition judgment test and particle size distribution measurement test ······ 6
7.2 Halide content test, copper plate corrosion test, copper mirror corrosion test and insulation resistance test ······ 6
7.3 Printability test, viscosity characteristic test, slump-in-printing test, slump-in-heating test and tackiness test ······ 6
7.4 Solder spreading test, flux efficacy and de-wetting test, solder ball test, wetting balance test and displacement detecting wetting test ······ 6
7.5 Colour reaction method (fluoride content test), flux content test, dryness test, ionic flux residue test and migration test ······ 7
8 Inspection ······ 7
9 Packaging ······ 7
10 Marking ······ 7
Annex A (normative) Characteristic evaluation table of solder paste ······ 8
Annex JA (informative) Comparison table between JIS and corresponding International Standard ······ 10

Foreword

This Japanese Industrial Standard has been revised by the Minister of Economy, Trade and Industry through deliberations at the Japanese Industrial Standards Committee as the result of proposal for revision of Japanese Industrial Standard submitted by The Japan Welding Engineering Society (JWES)/Japanese Standards Association (JSA) with a draft being attached, based on the provision of Article 12, paragraph (1) of the Industrial Standardization Act applied mutatis mutandis pursuant to the provision of Article 16 of the said Act. This edition replaces the previous edition (**JIS Z 3284-1** : 2020), which has been technically revised.

Attention is drawn to the possibility that some parts of this Standard may conflict with patent rights, published patent application or utility model rights. The relevant Minister and the Japanese Industrial Standards Committee are not responsible for identifying any of such patent rights, published patent application or utility model rights.

JIS Z 3284 series consists of the following 4 parts under the general title *Solder paste —*:

- *Part 1: Kinds and quality classification*
- *Part 2: Test methods for solder particle shape, surface condition judgment, and particle size distribution*
- *Part 3: Test methods for printability, viscosity, slump and tackiness*
- *Part 4: Test methods for wettability, solderball and spread*

Solder paste — Part 1: Kinds and quality classification

Introduction

This Japanese Industrial Standard has been prepared based on **IEC 61190-1-2** : 2014, Edition 3, with some modifications of the technical contents.

The vertical lines on both sides and dotted underlines indicate changes from the corresponding International Standard. A list of technical modifications with the explanations is given in Annex JA.

1 Scope

This Standard specifies requirements for the kinds and quality classification of solder pastes mainly used for wiring connections in electrical equipment, electronic equipment, communication equipment or the like, and for the manufacture and production of their components.

NOTE The International Standard corresponding to this Standard and the symbol of degree of correspondence are as follows.

IEC 61190-1-2 : 2014 *Attachment materials for electronic assembly — Part 1-2: Requirements for soldering pastes for high-quality interconnects in electronics assembly* (MOD)

In addition, symbols which denote the degree of correspondence in the contents between the relevant International Standard and **JIS** are IDT (identical), MOD (modified), and NEQ (not equivalent) according to **ISO/IEC Guide 21-1**.

2 Normative references

Part or all of the provisions of the following standards, through reference in this text, constitute provisions of this Standard. The most recent editions of the standards (including amendments) indicated below shall be applied.

JIS Z 3001-1 *Welding and allied processes — Vocabulary — Part 1: General*

JIS Z 3001-3 *Welding and allied processes — Vocabulary — Part 3: Soldering and brazing*

JIS Z 3197 *Test methods for soldering fluxes*

JIS Z 3282 *Soft solders — Chemical compositions and forms*

JIS Z 3284-2 *Solder paste — Part 2: Test methods for solder particle shape, surface condition judgment, and particle size distribution*

JIS Z 3284-3 *Solder paste — Part 3: Test methods for printability, viscosity, slump and tackiness*

JIS Z 3284-4 *Solder paste — Part 4: Test methods for wettability, solderball and*